

## IGBT Chip in NPT-technology

### FEATURES:

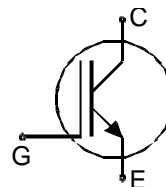
- 1200V NPT technology
- 200µm chip
- positive temperature coefficient
- easy paralleling

### This chip is used for:

- BUP 213

### Applications:

- drives



| Chip Type   | V <sub>CE</sub> | I <sub>Cn</sub> | Die Size                    | Package      | Ordering Code     |
|-------------|-----------------|-----------------|-----------------------------|--------------|-------------------|
| SIGC25T120C | 1200V           | 15A             | 5.71 x 4.53 mm <sup>2</sup> | sawn on foil | C67078-A4674-A001 |

### MECHANICAL PARAMETER:

|                                 |  |                 |
|---------------------------------|--|-----------------|
| Raster size                     | 5.71 x 4.53  | mm <sup>2</sup> |
| Emitter pad size                | 2 x ( 2.18 x 1.6 )   |                 |
| Gate pad size                   | 1.09 x 0.68  |                 |
| Area total / active             | 25.9 / 18.7  |                 |
| Thickness                       | 180  | µm              |
| Wafer size                      | 150  | mm              |
| Flat position                   | 270  | grd             |
| Max.possible chips per wafer    | 555 pcs  |                 |
| Passivation frontside           | Photoimide   |                 |
| Emitter metallization           | 3200 nm Al Si 1%   |                 |
| Collector metallization         | 1400 nm Ni Ag –system<br>suitable for epoxy and soft solder die bonding                      |                 |
| Die bond                        | electrically conductive glue or solder   |                 |
| Wire bond                       | Al, <500µm   |                 |
| Reject Ink Dot Size             | Ø 0.65mm ; max 1.2mm   |                 |
| Recommended Storage Environment | store in original container, in dry nitrogen,<br>< 6 month at an ambient temperature of 23°C |                 |

## MAXIMUM RATINGS:

| Parameter   | Symbol         | Value         | Unit               |
|---|----------------|---------------|--------------------|
| Collector-emitter voltage, $T_j=25\text{ °C}$         | $V_{CE}$       | 1200          | V                  |
| DC collector current, limited by $T_{jmax}$           | $I_C$          | <sup>1)</sup> | A                  |
| Pulsed collector current, $t_p$ limited by $T_{jmax}$ | $I_{cpuls}$    | 45            | A                  |
| Gate emitter voltage                                  | $V_{GE}$       | $\pm 20$      | V                  |
| Operating junction and storage temperature            | $T_j, T_{stg}$ | -55 ... +150  | $^{\circ}\text{C}$ |

<sup>1)</sup> depending on thermal properties of assembly

## STATIC CHARACTERISTICS (tested on chip), $T_j=25\text{ °C}$ , unless otherwise specified:

| Parameter                            | Symbol        | Conditions                 | Value |      |      | Unit          |
|--------------------------------------|---------------|----------------------------|-------|------|------|---------------|
|                                      |               |                            | min.  | typ. | max. |               |
| Collector-emitter breakdown voltage  | $V_{(BR)CES}$ | $V_{GE}=0V, I_C=1mA$       | 1200  |      |      | V             |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | $V_{GE}=15V, I_C=15A$      | 2.0   | 2.5  | 3.0  |               |
| Gate-emitter threshold voltage       | $V_{GE(th)}$  | $I_C=0.6mA, V_{GE}=V_{CE}$ | 4.5   | 5.5  | 6.5  |               |
| Zero gate voltage collector current  | $I_{CES}$     | $V_{CE}=1200V, V_{GE}=0V$  |       |      | 1.9  | $\mu\text{A}$ |
| Gate-emitter leakage current         | $I_{GES}$     | $V_{CE}=0V, V_{GE}=20V$    |       |      | 480  | nA            |

## ELECTRICAL CHARACTERISTICS (tested at component):

| Parameter                    | Symbol     | Conditions                                | Value |      |      | Unit |
|------------------------------|------------|---|-------|------|------|------|
|                              |            |   | min.  | typ. | max. |      |
| Input capacitance            | $C_{iss}$  | $V_{CE}=25V,$<br>$V_{GE}=0V,$<br>$f=1MHz$ | -     | 1000 | -    | pF   |
| Output capacitance           | $C_{oss}$  |   | -     | 150  | -    |      |
| Reverse transfer capacitance | $C_{riss}$ |   | -     | 70   | -    |      |

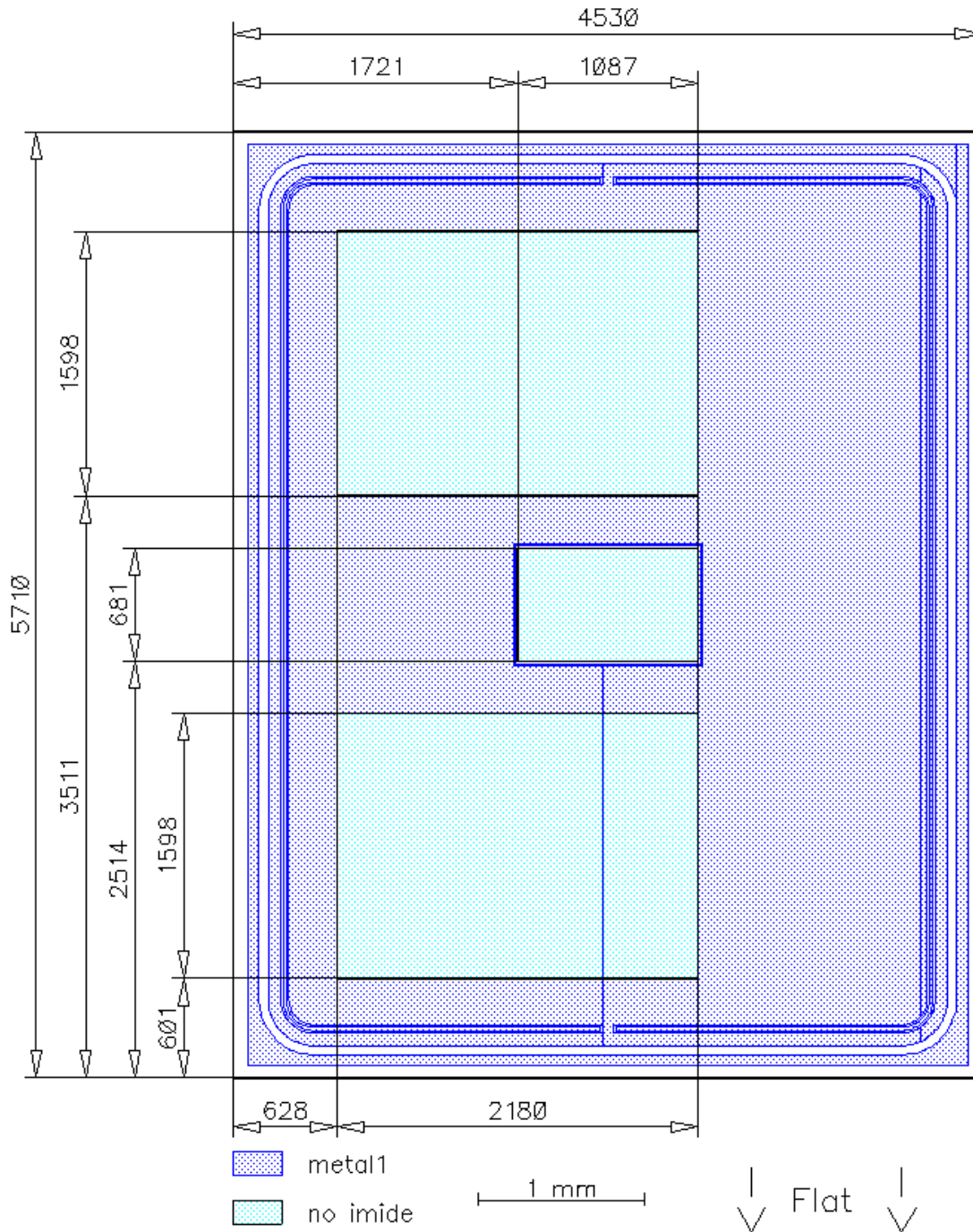
## SWITCHING CHARACTERISTICS (tested at component), Inductive Load

| Parameter           | Symbol       | Conditions <sup>1)</sup>  | Value |      |      | Unit |
|---------------------|--------------|---|-------|------|------|------|
|                     |              |   | min.  | typ. | max. |      |
| Turn-on delay time  | $t_{d(on)}$  | $T_j=125\text{ °C}$<br>$V_{CC}=600V,$<br>$I_C=15A,$<br>$V_{GE}=+15/-15V,$<br>$R_G=82\Omega$ | -     | 55   |      | ns   |
| Rise time           | $t_r$        |   | -     | 45   |      |      |
| Turn-off delay time | $t_{d(off)}$ |   | -     | 400  |      |      |
| Fall time           | $t_f$        |   | -     | 70   |      |      |

<sup>1)</sup> values also influenced by parasitic L- and C- in measurement and package.

**CHIP DRAWING:**

Die-Size 4530  $\mu\text{m}$  x 5710  $\mu\text{m}$



**FURTHER ELECTRICAL CHARACTERISTICS:**

|  |        |               |
|--|--------|---------------|
| This chip data sheet refers to the device data sheet | BUP213 | Package TO220 |
|--|--------|---------------|

**DESCRIPTION:**

AQL 0,65 for visual inspection according to failure catalog

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Test-Normen Villach/Prüffeld

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